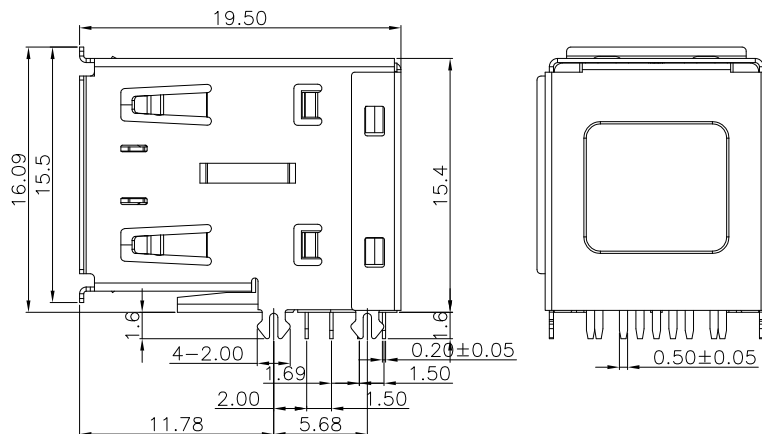
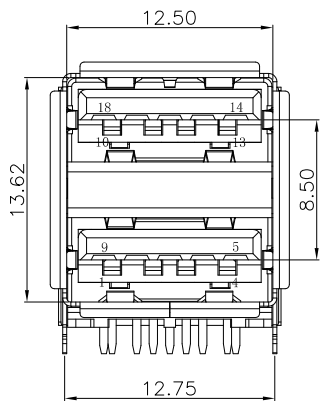


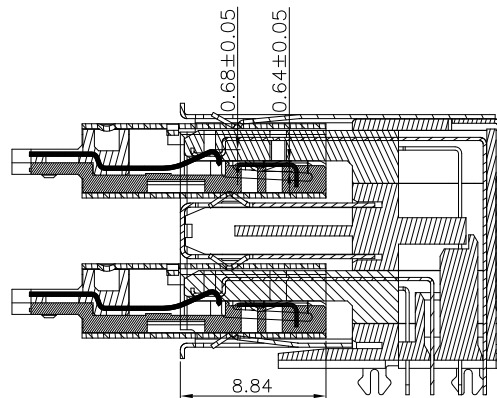
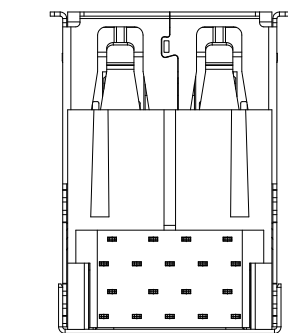
Recommended PCB Layout TOP VIEW

RoHS
Compliant

Pin Number	Signal Name	Pin Number	Signal Name
1/10	VBUS	5/14	SSRX-
2/11	D-	6/15	SSRX+
3/12	D+	7/16	GND
4/13	GND	8/17	SSTX-
Shell	Shield	9/18	SSTX+



Reference Mating Drawing



1. Material:

Contacts: PHOSPHOR BRONZE 0.2t
 Insulator/PLUG: PA9T+45% G.F. UL 94V-0, BLUE
 Shell/Rear Shell: SUS301 0.25t
 Spring: SUS301 0.25t

2. Mechanical:

Mating: 35N max.
 Withdrawal Force: 10N min, 5000 cycles 8N Min
 Durability: 5000 cycles Min

3. Electrical:

Current-max: 1.8A (PIN1, 4), OTHER CONTACTS 0.25A
 Voltage-max: 30V
 Withstanding Voltage: 300V AC
 Contact Resistance : 30mΩ (PIN1, 4), OTHER CONTACTS 50mΩ
 Insulation Resistance : 100MΩ min.

4. Plating:

Contacts: Gold PLATED ON CONTACT AREA,
 Tin PLATED ON SOLDERING,
 NICKEL UNDER PLATING OVERALL
 SHELL: Nickel Over All Plating

5. Environmental

Temperature Range: -55° C ~ +85° C

ORDER INFORMATION

SERIES NO.	Contact Plated	Packing	Shell Plated	Shell Leg	Housing Color
U30DD - A - R - R	XX	X	D	2	W -67
USB 3.0 DIP Dual Layers Type	A: A Type R: Receptacle R: Right Angle	G1: Gold Flash G5: 30u"	2: T&R 3: Tray	Stainless D: Nickel	2: 2X Straight W: Blue PA9T

REV.	REVISION RECORD	DATE	General Tolerances		
A	Original	12/19/16'	LINEAR 0.0 ± 0.35 0.00 ± 0.20	ANGLES ± 3°	
B	Revised	08/01/18'	UNIT: mm		
C	Revised	10/11/18'	A4	NAME DATE	
			APPROVED	MICHAEL	
			DESIGNER	CONNER	
			DRAWN	ANGEL	
			TITLE: USB 3.0 A Female DIP RA Shell Boardlock Dual Layers		
			DWG.NO.: U30DDARRXXD2W-67	REV. C	
			SCALE 1 : 1	SHEET 1 OF 1	